
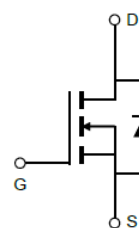




20V N-Channel Trench MOSFET(Preliminary)

General Description	Product Summary
<ul style="list-style-type: none">Trench Power technologyLow $R_{DS(ON)}$Low Gate ChargeOptimized for fast-switching applications Applications <ul style="list-style-type: none">Synchronous Rectification in DC/DC and AC/DC ConvertersIsolated DC/DC Converters in Telecom and Industrial	V_{DS} 20V I_D (at $V_{GS}=10V$) 150A $R_{DS(ON)}$ (at $V_{GS}=10V$) < 2.8m Ω $R_{DS(ON)}$ (at $V_{GS}=4.5V$) < 3.0m Ω $R_{DS(ON)}$ (at $V_{GS}=2.5V$) < 4.4m Ω 100% UIS Tested 

TO-220



Part Number	Package Type	Form	Marking
TTP150N02GT	TO-220	Tube	150N02GT

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^B	$T_C=25^{\circ}\text{C}$	I_D 105	A
	$T_C=100^{\circ}\text{C}$	105	
Pulsed Drain Current ^A	I_{DM}	450	A
Avalanche Current ^A	I_{AS}	32	A
Single Pulse Avalanche Energy ^A	$L=0.3\text{mH}$ E_{AS}	153.6	mJ
Power Dissipation ^C	$T_C=25^{\circ}\text{C}$	P_D 127	W
	$T_C=100^{\circ}\text{C}$	63.6	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^{\circ}\text{C}$

Thermal Characteristics

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Case	Steady-State $R_{\theta JC}$	1.18	$^{\circ}\text{C/W}$
Maximum Junction-to-Ambient	Steady-State $R_{\theta JA}$	100	



Electrical Characteristics(T _J =25°C unless otherwise noted)							
Symbol	Parameter	Conditions		Value			Units
				Min	Typ	Max	
STATIC PARAMETERS							
B _V DSS	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V		20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V	T _J =25°C			1	μA
			T _J =100°C				
I _{GSS}	Gate-Body Leakage Current	V _{DS} =0V, V _{GS} =± 20V				± 100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA		0.5	0.7	1.2	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =30A			2.2	2.8	mΩ
		V _{GS} =4.5V, I _D =30A			2.3	3.0	mΩ
		V _{GS} =2.5V, I _D =30A			3.4	4..4	mΩ
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =20A			21		S
V _{SD}	Diode Forward Voltage	I _S =50A, V _{GS} =0V				1	V
I _S	Maximum Body-Diode Continuous Current ^B					105	A
DYNAMIC PARAMETERS							
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, f =1MHz _Z			6073		pF
C _{oss}	Output Capacitance				1540		
C _{rss}	Reverse Transfer Capacitance				1171		
SWITCHING PARAMETERS							
Q _g (10V)	Total Gate Charge	V _{GS} =10V, V _{DS} =10V, I _D =50A			165		nC
Q _{gs}	Gate Source Charge				9		
Q _{gd}	Gate Drain Charge				30		
t _{D(on)}	Turn-On Delay Time	V _{GS} =10V, V _{DS} =10V, I _D =50A, R _G =3Ω			13		ns
t _r	Turn-On Rise Time				17		
T _{D(off)}	Turn-Off Delay Time				19		
t _f	Turn-Off Fall Time				16		
t _{rr}	Body Diode Reverse Recovery Time	I _F =50A, di/dt =100A/μs			17		ns
Q _{rr}	Body Diode Reverse Recovery Charge				15		nC

A. Single pulse width limited by maximum junction temperature.

B. The maximum current rating is package limited.

C. The power dissipation P_D is based on $T_{J(MAX)} = 175^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

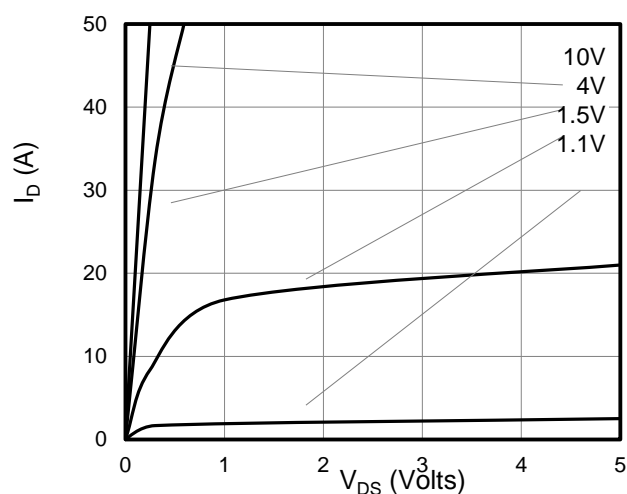


Figure 1: On-Region Characteristics

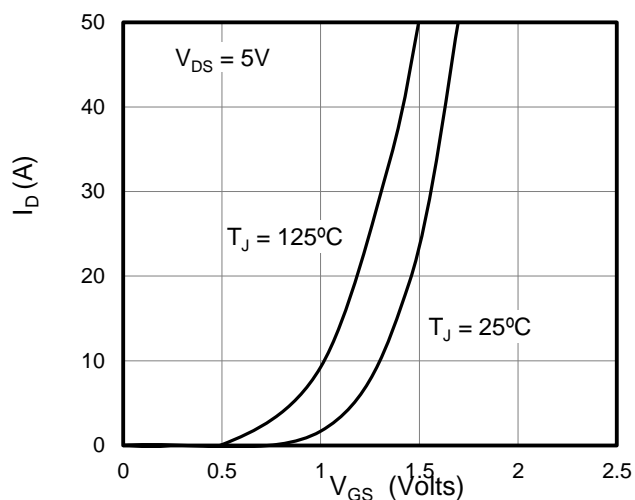


Figure 2: Transfer Characteristics

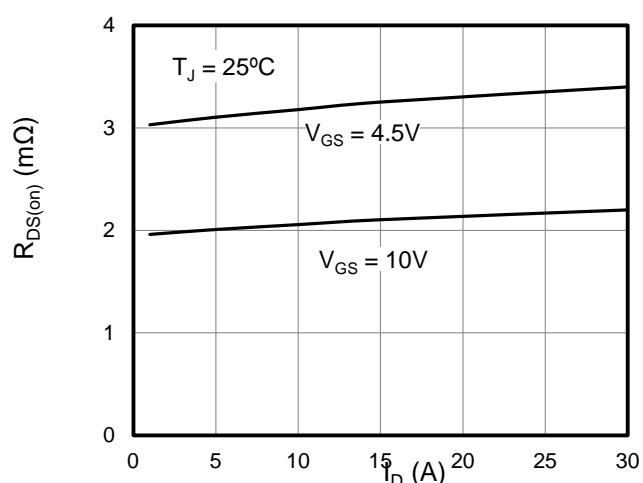


Figure 3: On-Resistance vs. Drain Current

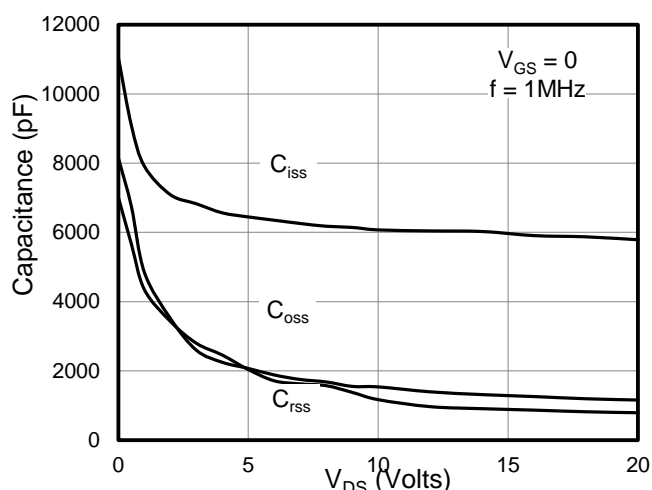


Figure 4: Capacitance Characteristics

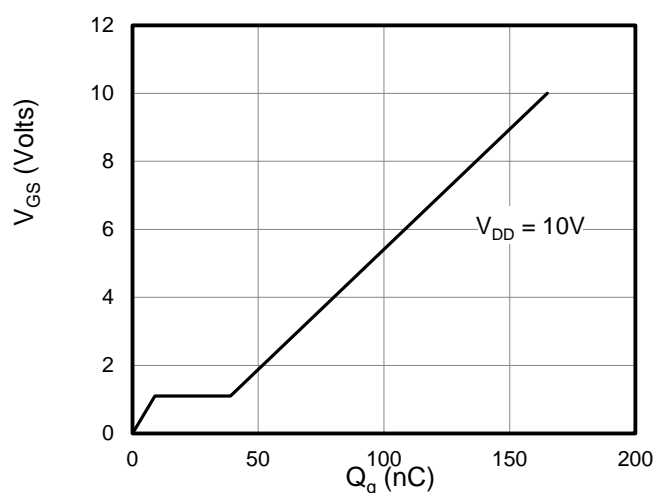


Figure 5: Gate Charge Characteristics

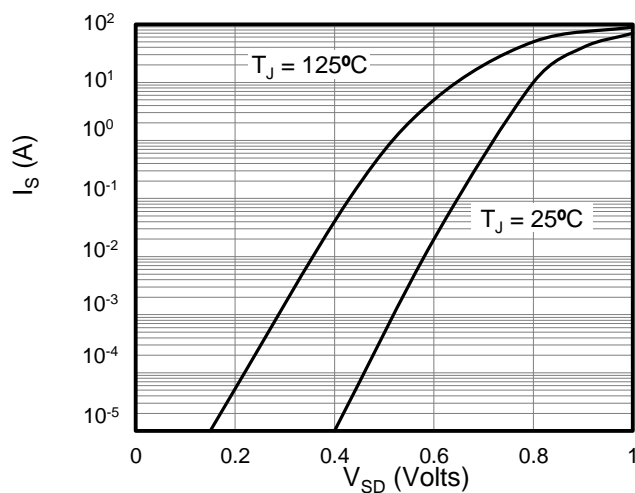


Figure 6: Body Diode Forward Voltage



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

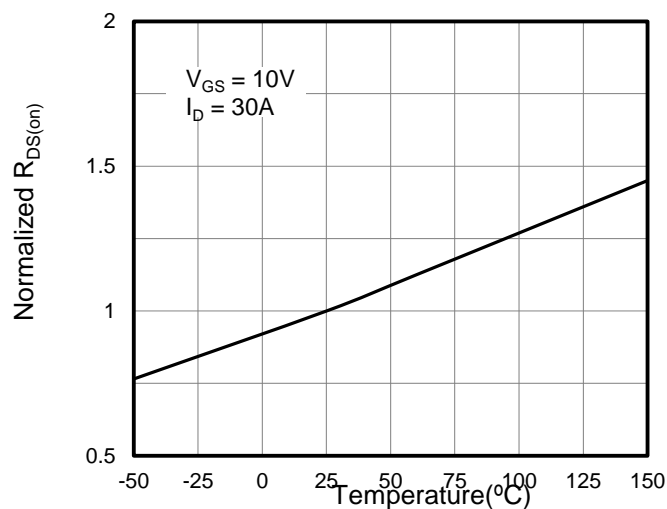


Figure 7: On-Resistance vs. Junction Temperature

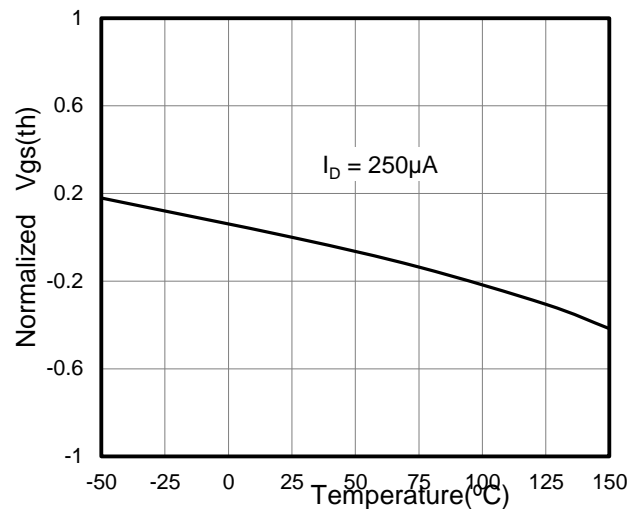
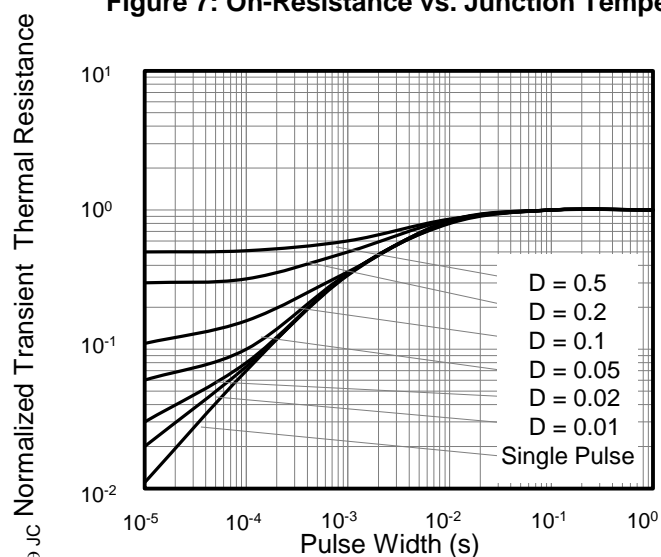
Figure 8: $V_{GS(th)}$ vs. Junction Temperature

Figure 11: Normalized Transient Thermal Resistance

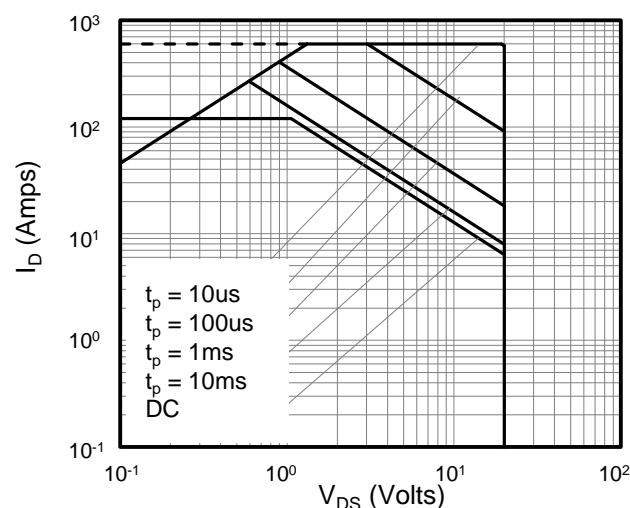


Figure 12: Safe Operating Area

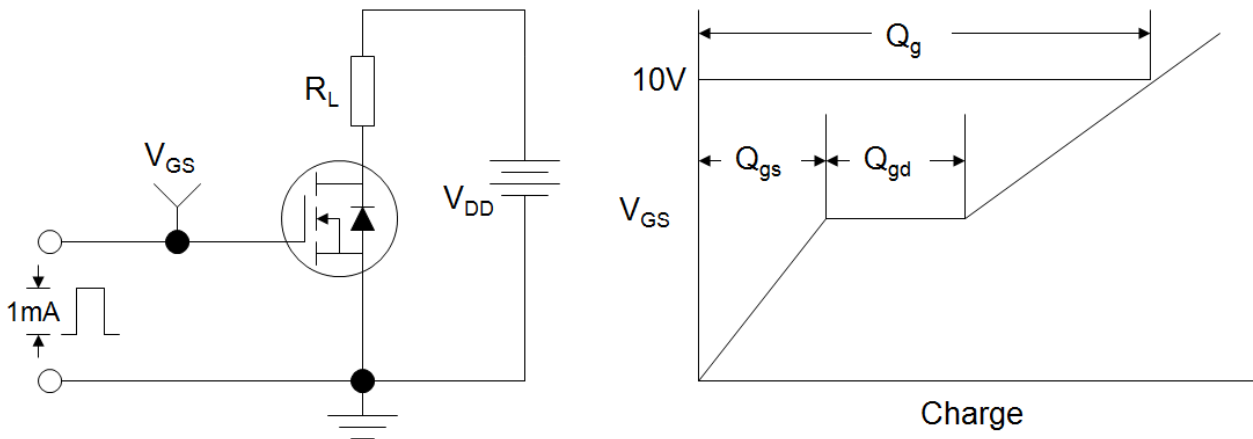


Figure A: Gate Charge Test Circuit and Waveforms

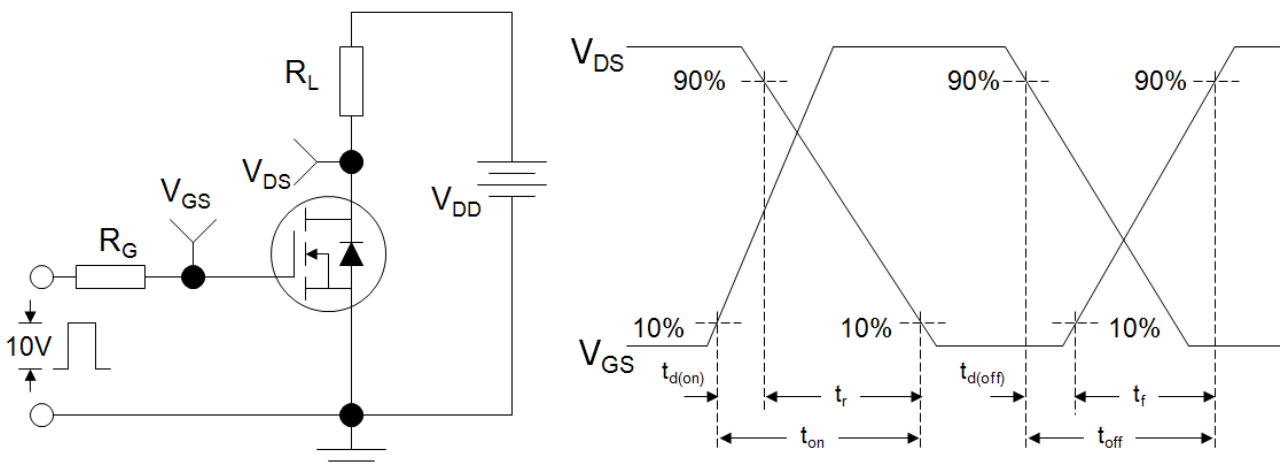


Figure B: Resistive Switching Test Circuit and Waveforms

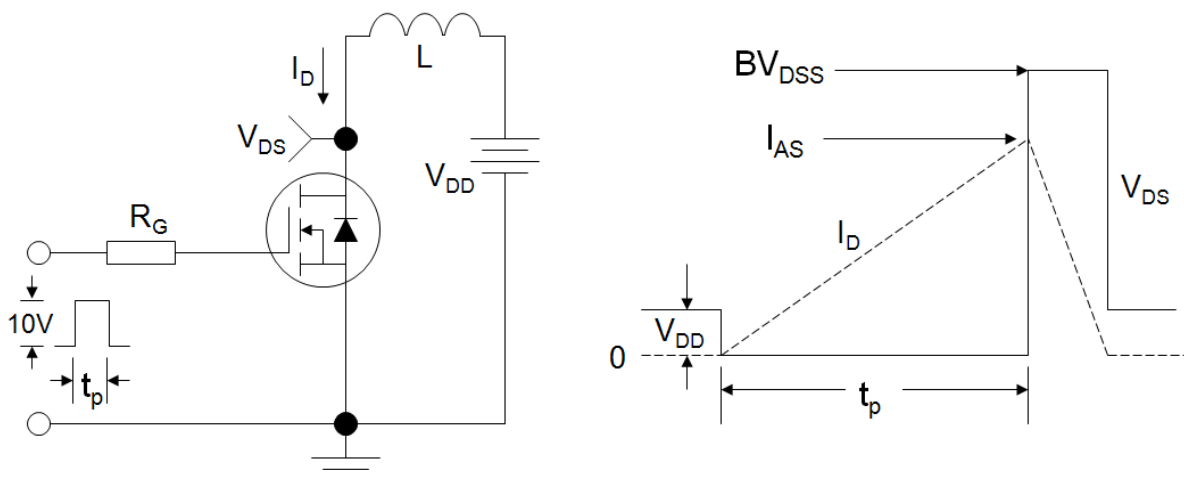


Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms



Wuxi Unigroup Microelectronics CO.,LTD.

Technical drawing of a three-pin electrical plug, showing three views: front, side, and top.

Front View (Left): Shows the overall dimensions D (total height), $D1$ (height to the top of the mounting bracket), E (width), and A (height of the mounting bracket). The mounting bracket has a central circular hole with diameter ϕP . The three pins are shown at the bottom, with dimensions $L1$ (pin length), $b2$ (pin width), b (pin diameter), e (pin spacing), and $e1$ (total pin width). The bottom of the plug has a dimension C .

Side View (Middle): Shows the side profile with dimensions A (total height), $A1$ (height of the mounting bracket), H (height of the pin), and $A2$ (height of the pin).

Top View (Right): Shows the top of the plug with dimensions $E3$ (width of the mounting bracket) and $D2$ (height of the mounting bracket).

Unit: mm		
Symbol	Min.	Max.
A	4.37	4.77
A1	1.25	1.45
A2	2.20	2.60
b	0.70	0.95
b2	1.17	1.47
c	0.40	0.65
D	15.10	16.10
D1	8.80	9.40
D2	5.50	-

Unit: mm		
Symbol	Min.	Max.
E	9.70	10.30
E3	7.00	—
e	2.54BSC	
e1	5.08BSC	
H1	6.25	6.85
L	12.75	13.80
L1	—	3.40
P	3.40	3.80
Q	2.60	3.00



Disclaimer

All product specifications and data are subject to change without notice.

For documents and material available from this datasheet, Wuxi Unigroup does not warrant or assume any legal liability or responsibility for the accuracy, completeness of any product or technology disclosed hereunder.

No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document or by any conduct of Wuxi Unigroup.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling Wuxi Unigroup products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Wuxi Unigroup for any damages arising or resulting from such use or sale.

Wuxi Unigroup disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Wuxi Unigroup's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

Wuxi Unigroup Microelectronics CO., LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all Wuxi Unigroup products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

Information (including circuit diagrams and circuit parameters) herein is for example only. It is not guaranteed for volume production. Wuxi Unigroup believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.